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SHEET 1 OF 1

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						based on PCT/FR04/50335	
LIST OF REFERENCES CITED BY APPLICANT				APPLICANT			
				Jean BRUN, et al.			
				FILING DATE		GROUP	
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	AA	2001/00 2044 02044	05/31/01	BALL et al.			
	AB	5 135 606	08/04/92	KATO et al.			
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		DOCUMENT NUMBER	DATE	COUNTRY		TRANSLATION YES NO	
	AO	1 270 694	01/02/03	EP			NO
	AP	07-320543	12/08/95	JP (Abstract only)			NO
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